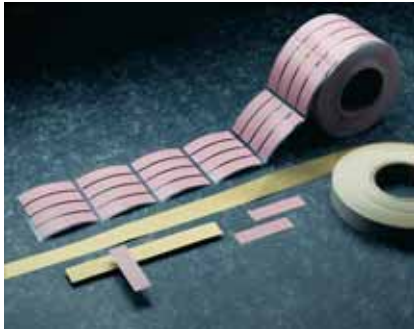


High Performance Insulator for Low-Pressure Applications

Features and Benefits

- Thermal impedance:
0.45°C-in²/W (@50 psi)
- High value material
- Smooth and highly compliant surface
- Electrically isolating



The Sil-Pad 800 family of thermally conductive insulation materials is designed for applications requiring high thermal performance and electrical isolation. These applications also typically have low mounting pressures for component clamping.

Sil-Pad 800 material combines a smooth and highly compliant surface characteristic with high thermal conductivity. These features optimize the thermal resistance properties at low pressure.

Applications requiring low component clamping forces include discrete semiconductors (TO-220, TO-247 and TO-218) mounted with spring clips. Spring clips assist with quick assembly but apply a limited amount of force to the semiconductor. The smooth surface texture of Sil-Pad 800 minimizes interfacial thermal resistance and maximizes thermal performance.

TYPICAL PROPERTIES OF SIL-PAD 800						
PROPERTY		IMPERIAL VALUE		METRIC VALUE		TEST METHOD
Color		Gold		Gold		Visual
Reinforcement Carrier		Fiberglass		Fiberglass		—
Thickness (inch) / (mm)		0.005		0.127		ASTM D374
Hardness (Shore A)		91		91		ASTM D2240
Elongation (%45° to Warp and Fill)		20		20		ASTM D412
Tensile Strength (psi) / (MPa)		1700		12		ASTM D412
Continuous Use Temp (°F) / (°C)		-76 to 356		-60 to 180		—
ELECTRICAL						
Dielectric Breakdown Voltage (Vac)		1700		1700		ASTM D149
Type 3 Electrodes		3000		3000		ASTM D149
Dielectric Constant (1000 Hz)		6.0		6.0		ASTM D150
Volume Resistivity (Ohm-meter)		10 ¹⁰		10 ¹⁰		ASTM D257
Flame Rating		V-O		V-O		U.L. 94
THERMAL						
Thermal Conductivity (W/m-K)		1.6		1.6		ASTM D5470
THERMAL PERFORMANCE vs PRESSURE						
Pressure (psi)		10	25	50	100	200
TO-220 Thermal Performance (°C/W)		3.56	3.01	2.45	2.05	1.74
Thermal Impedance (°C-in²/W) (1)		0.92	0.60	0.45	0.36	0.29
1) The ASTM D5470 test fixture was used. The recorded value includes interfacial thermal resistance. These values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.						

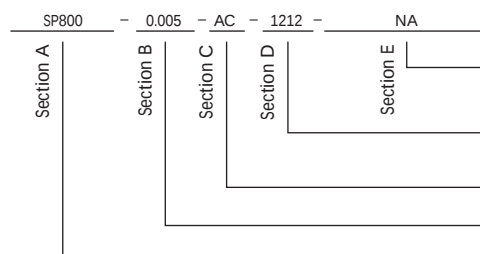
Typical Applications Include:

- Power supplies
- Automotive electronics
- Motor controls
- Power semiconductors

Configurations Available:

- Sheet form, die-cut parts and roll form
- With or without pressure sensitive adhesive

Building a Part Number



Standard Options

NA = Selected standard option. If not selecting a standard option, insert company name, drawing number, and revision level.

1212 = Standard configuration dash number, 1212 = 12" x 12" sheets, 12/250 = 12" x 250' rolls, or 00 = custom configuration

AC = Adhesive, one side
00 = No adhesive

Standard thicknesses available: 0.005"

SP800 = Sil-Pad 800 Material

Note: To build a part number, visit our website at www.bergquistcompany.com.

Sil-Pad®: U.S. Patents 4,574,879; 4,602,125; 4,602,678; 4,685,987; 4,842,911 and others



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<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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